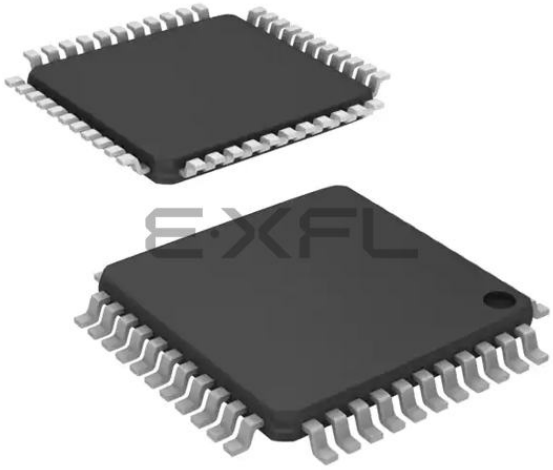

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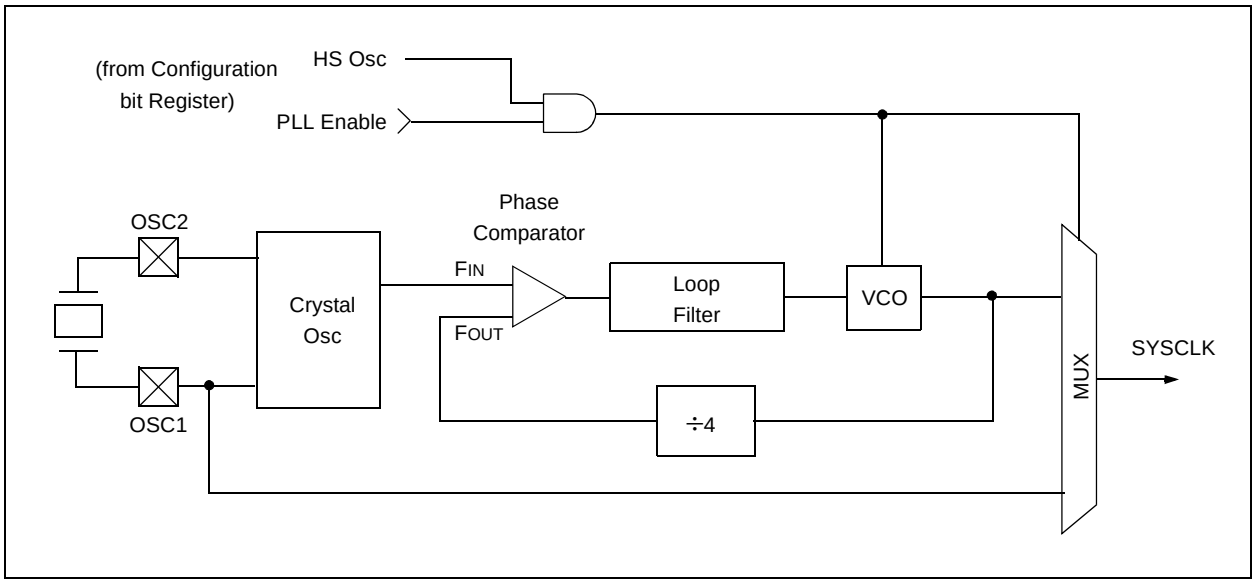
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	32
Program Memory Size	24KB (12K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1408 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf4539-i-pt

FIGURE 2-5: PLL BLOCK DIAGRAM



2.5 Effects of SLEEP Mode on the On-Chip Oscillator

When the device executes a SLEEP instruction, the oscillator is turned off and the device is held at the beginning of an instruction cycle (Q1 state). With the oscillator off, the OSC1 and OSC2 signals will stop oscillating. Since all the transistor switching currents have been removed, SLEEP mode achieves the lowest current consumption of the device (only leakage currents). Enabling any on-chip feature that will operate during SLEEP will increase the current consumed during SLEEP. The user can wake from SLEEP through external RESET, Watchdog Timer Reset, or through an interrupt.

2.6 Power-up Delays

Power-up delays are controlled by two timers, so that no external RESET circuitry is required for most applications. The delays ensure that the device is kept in RESET, until the device power supply and clock are stable. For additional information on RESET operation, see Section 3.0.

The first timer is the Power-up Timer (PWRT), which optionally provides a fixed delay of 72 ms (nominal) on power-up only (POR and BOR). The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable.

With the PLL enabled (HS/PLL Oscillator mode), the time-out sequence following a Power-on Reset is different from other Oscillator modes. The time-out sequence is as follows:

1. The PWRT time-out is invoked after a POR time delay has expired.
2. The Oscillator Start-up Timer (OST) is invoked. However, this is still not a sufficient amount of time to allow the PLL to lock at high frequencies.
3. The PWRT timer is used to provide an additional fixed 2 ms (nominal) time-out to allow the PLL ample time to lock to the incoming clock frequency.

TABLE 2-2: OSC1 AND OSC2 PIN STATES IN SLEEP MODE

OSC Mode	OSC1 Pin	OSC2 Pin
ECIO	Floating	Configured as PORTA, bit 6
EC	Floating	At logic low
HS	Feedback inverter disabled, at quiescent voltage level	Feedback inverter disabled, at quiescent voltage level

Note: See Table 3-1 in the **"Reset"** section, for time-outs due to SLEEP and $\overline{\text{MCLR}}$ Reset.

FIGURE 3-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})

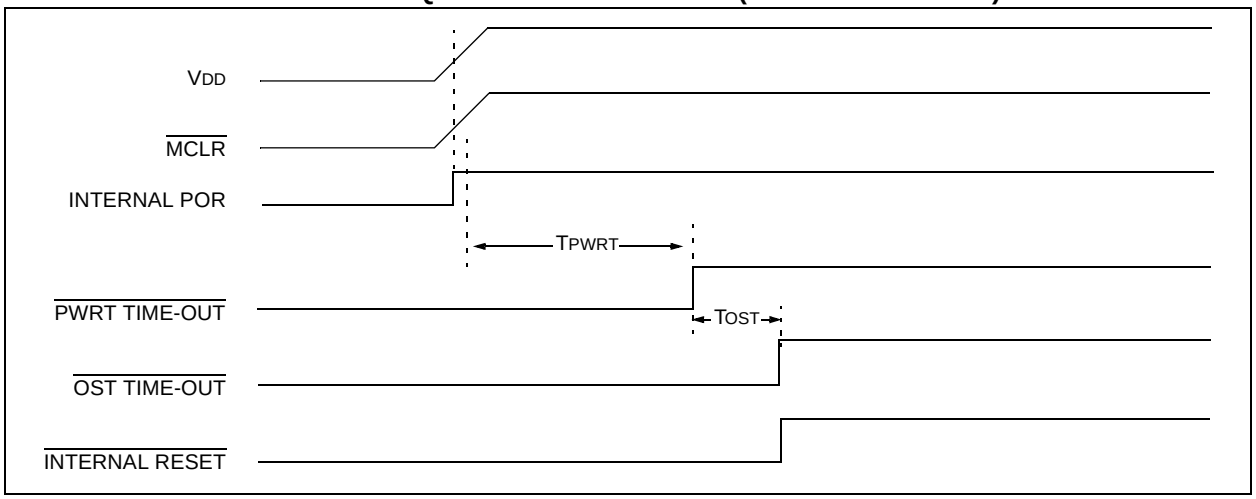


FIGURE 3-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 1

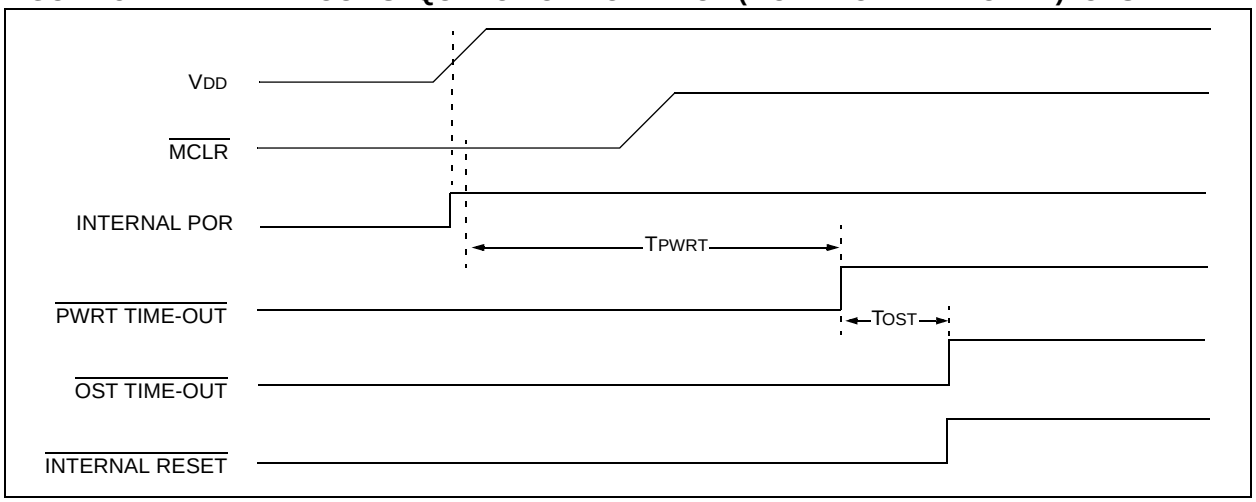
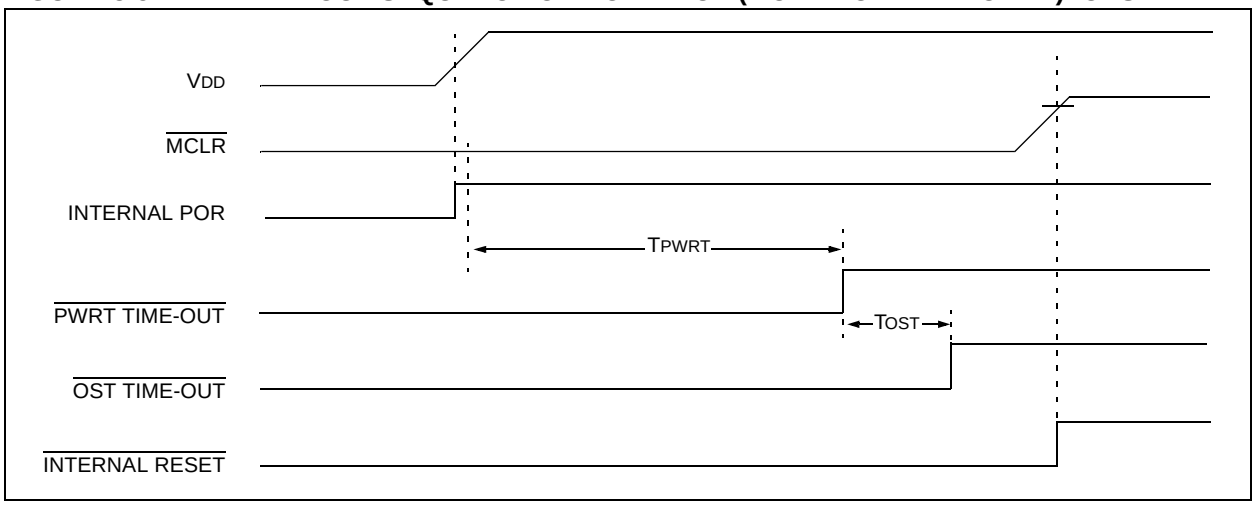


FIGURE 3-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 2



4.0 MEMORY ORGANIZATION

There are three memory blocks in Enhanced MCU devices. These memory blocks are:

- Program Memory
- Data RAM
- Data EEPROM

Data and program memory use separate busses, which allows for concurrent access of these blocks.

Additional detailed information for FLASH program memory and Data EEPROM is provided in Section 5.0 and Section 6.0, respectively.

4.1 Program Memory Organization

A 21-bit program counter is capable of addressing the 2-Mbyte program memory space. Accessing a location between the physically implemented memory and the top of the 2-MByte range will cause a read of all '0's (a `NOP` instruction).

The PIC18F2539 and PIC18F4539 each have a total of 24 Kbytes, or 12K of single word instructions of FLASH memory, from addresses 0000h to 5FFFh. The next 8 Kbytes beyond this space (from 6000h to 7FFFh) are reserved for the Motor Control kernel; accessing locations in this range will return random information.

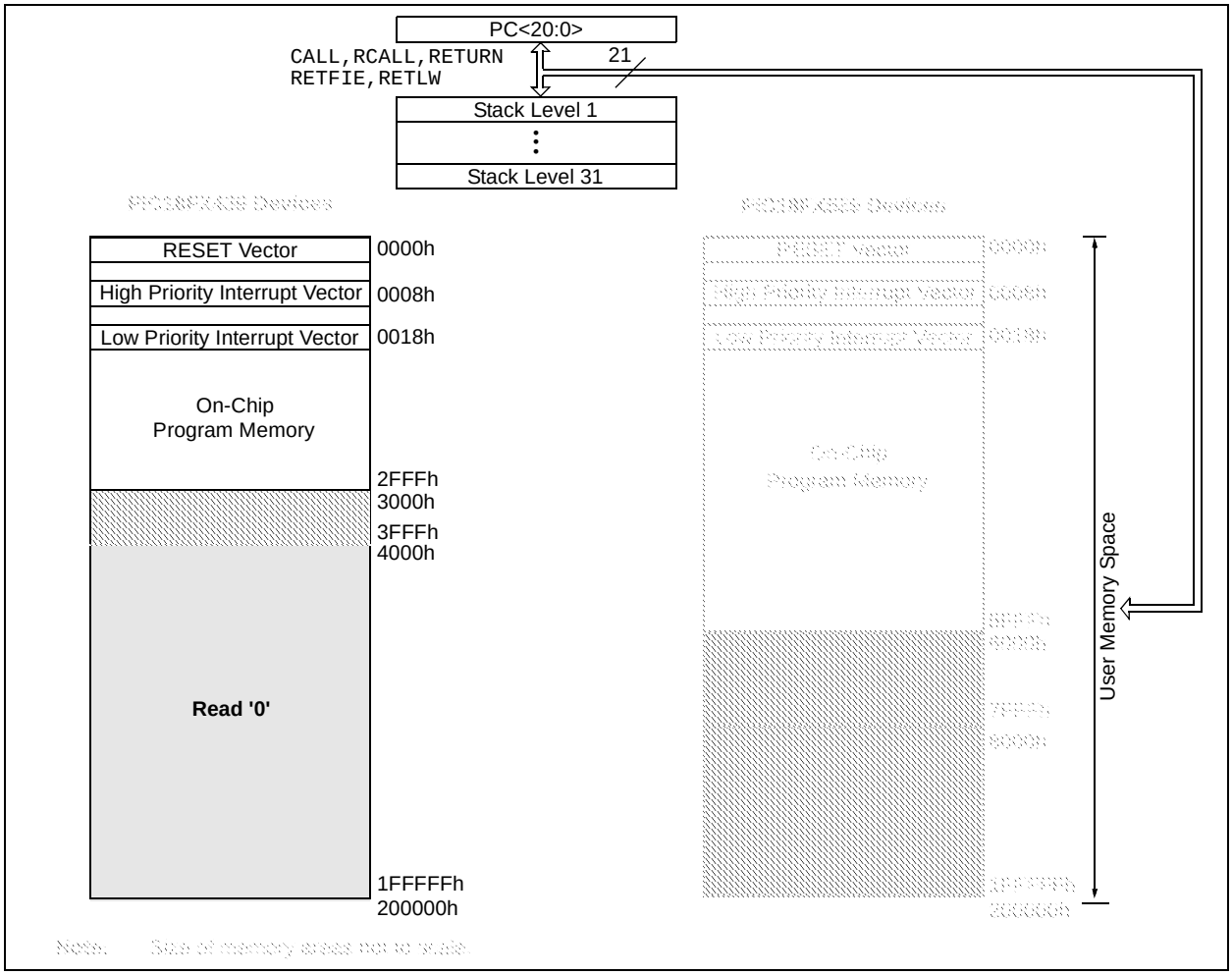
The PIC18F2439 and PIC18F4439 each have 12 Kbytes, or 6K of single word instructions of FLASH memory, from addresses 0000h to 2FFFh. The next 4 Kbytes of this space (from 3000h to 3FFFh) are reserved for the Motor Control kernel; accessing locations in this range will return random information.

The RESET vector address for all devices is at 0000h, and the interrupt vector addresses are at 0008h and 0018h.

The memory maps for the PIC18FX439 and PIC18FX539 devices are shown in Figure 4-1.

Note:	The ProMPT Motor Control kernel is identical for all PIC18FXX39 devices, regardless of the difference in reserved block size between PIC18FX439 and PIC18FX539 devices

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR PIC18FXX39 DEVICES



5.0 FLASH PROGRAM MEMORY

The FLASH Program Memory is readable, writable, and erasable during normal operation over the entire VDD range.

A read from program memory is executed on one byte at a time. A write to program memory is executed on blocks of 8 bytes at a time. Program memory is erased in blocks of 64 bytes at a time. A bulk erase operation may not be issued from user code.

Writing or erasing program memory will cease instruction fetches until the operation is complete. The program memory cannot be accessed during the write or erase, therefore, code cannot execute. An internal programming timer terminates program memory writes and erases.

A value written to program memory does not need to be a valid instruction. Executing a program memory location that forms an invalid instruction results in a NOP.

5.1 Table Reads and Table Writes

In order to read and write program memory, there are two operations that allow the processor to move bytes between the program memory space and the data RAM:

- Table Read (TBLRD)
- Table Write (TBLWT)

The program memory space is 16-bits wide, while the data RAM space is 8-bits wide. Table Reads and Table Writes move data between these two memory spaces through an 8-bit register (TABLAT).

Table Read operations retrieve data from program memory and places it into the data RAM space. Figure 5-1 shows the operation of a Table Read with program memory and data RAM.

Table Write operations store data from the data memory space into holding registers in program memory. The procedure to write the contents of the holding registers into program memory is detailed in Section 5.5, “Writing to FLASH Program Memory”. Figure 5-2 shows the operation of a Table Write with program memory and data RAM.

Table operations work with byte entities. A table block containing data, rather than program instructions, is not required to be word aligned. Therefore, a table block can start and end at any byte address. If a Table Write is being used to write executable code into program memory, program instructions will need to be word aligned.

FIGURE 5-1: TABLE READ OPERATION

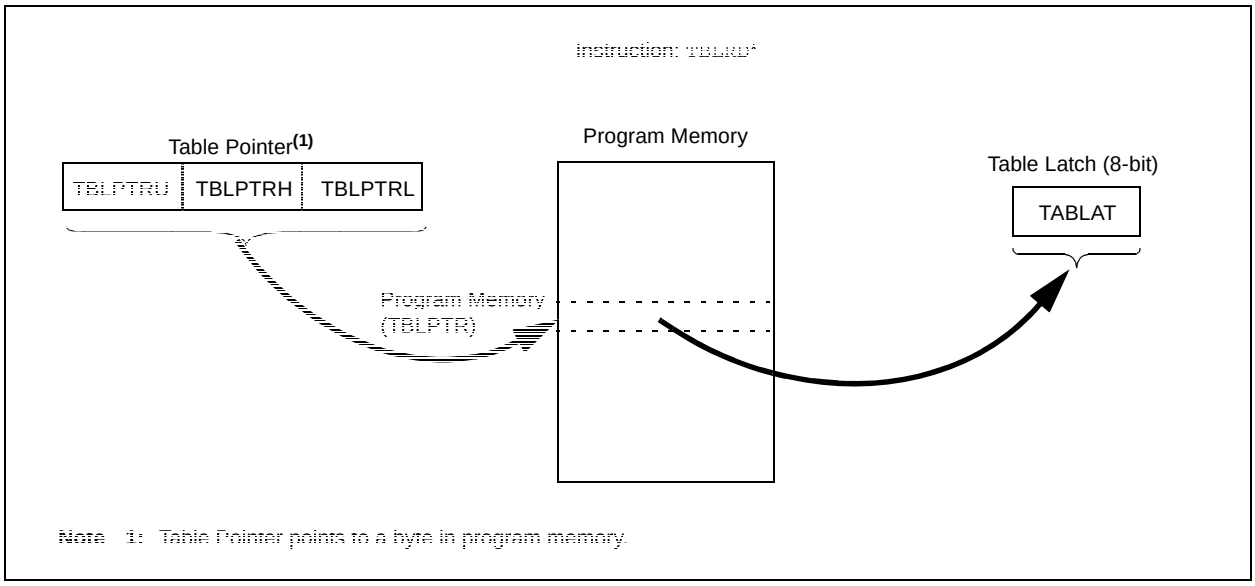
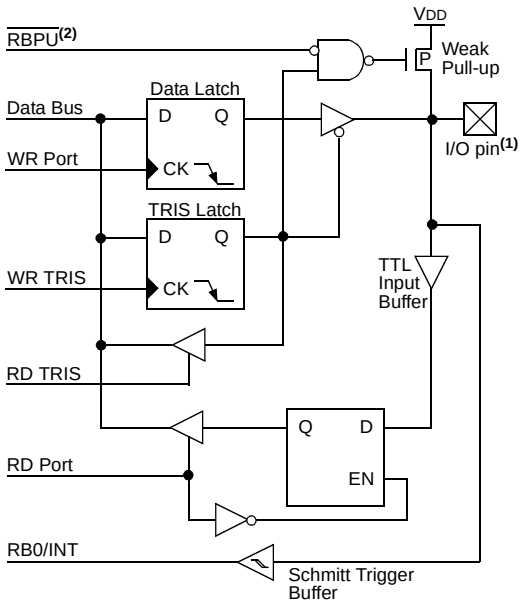
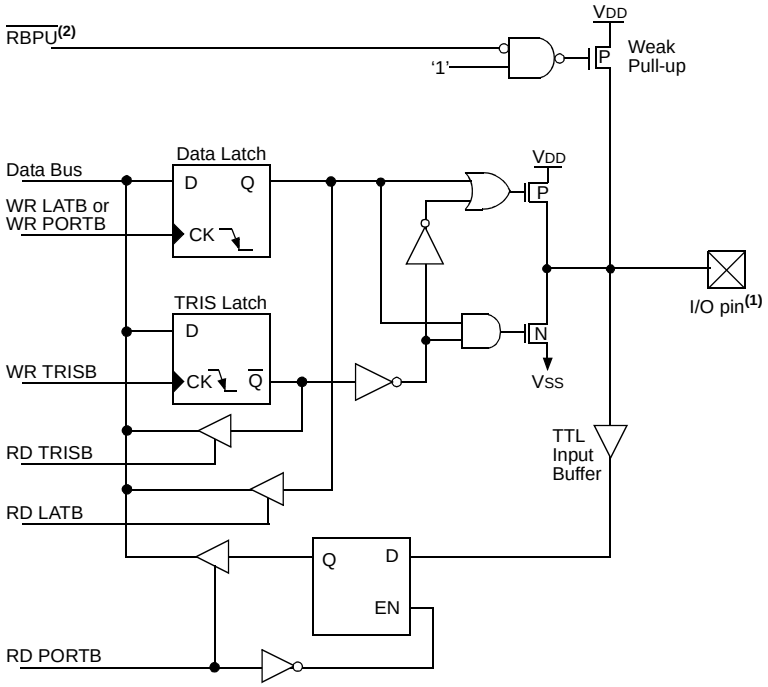


FIGURE 9-5: BLOCK DIAGRAM OF RB2:RB0 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

FIGURE 9-6: BLOCK DIAGRAM OF RB3 PIN



Note 1: I/O pin has diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate DDR bit(s) and clear the $\overline{\text{RBPU}}$ bit (INTCON2<7>).

TABLE 9-7: PORTD FUNCTIONS

Name	Bit#	Buffer Type	Function
RD0/PSP0	bit0	ST/TTL(1)	Input/output port pin or parallel slave port bit0.
RD1/PSP1	bit1	ST/TTL(1)	Input/output port pin or parallel slave port bit1.
RD2/PSP2	bit2	ST/TTL(1)	Input/output port pin or parallel slave port bit2.
RD3/PSP3	bit3	ST/TTL(1)	Input/output port pin or parallel slave port bit3.
RD4/PSP4	bit4	ST/TTL(1)	Input/output port pin or parallel slave port bit4.
RD5/PSP5	bit5	ST/TTL(1)	Input/output port pin or parallel slave port bit5.
RD6/PSP6	bit6	ST/TTL(1)	Input/output port pin or parallel slave port bit6.
RD7/PSP7	bit7	ST/TTL(1)	Input/output port pin or parallel slave port bit7.

Legend: ST = Schmitt Trigger input, TTL = TTL input

Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffers when in Parallel Slave Port mode.

TABLE 9-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
LATD	LATD Data Output Register								xxxx xxxx	uuuu uuuu
TRISD	PORTD Data Direction Register								1111 1111	1111 1111
TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PORTD.

9.5 PORTE, TRISE and LATE Registers

This section is only applicable to the PIC18F4X39 devices.

PORTE is a 3-bit wide, bi-directional port. The corresponding Data Direction register is TRISE. Setting a TRISE bit (= 1) will make the corresponding PORTE pin an input (i.e., put the corresponding output driver in a High Impedance mode). Clearing a TRISE bit (= 0) will make the corresponding PORTE pin an output (i.e., put the contents of the output latch on the selected pin).

The Data Latch register (LATE) is also memory mapped. Read-modify-write operations on the LATE register reads and writes the latched output value for PORTE.

PORTE has three pins (RE0/AN5/$\overline{RD}$, RE1/AN6/$\overline{WR}$ and RE2/AN7/$\overline{CS}$) which are individually configurable as inputs or outputs. These pins have Schmitt Trigger input buffers.

Register 9-1 shows the TRISE register, which also controls the parallel slave port operation.

PORTE pins are multiplexed with analog inputs. When selected as an analog input, these pins will read as '0's.

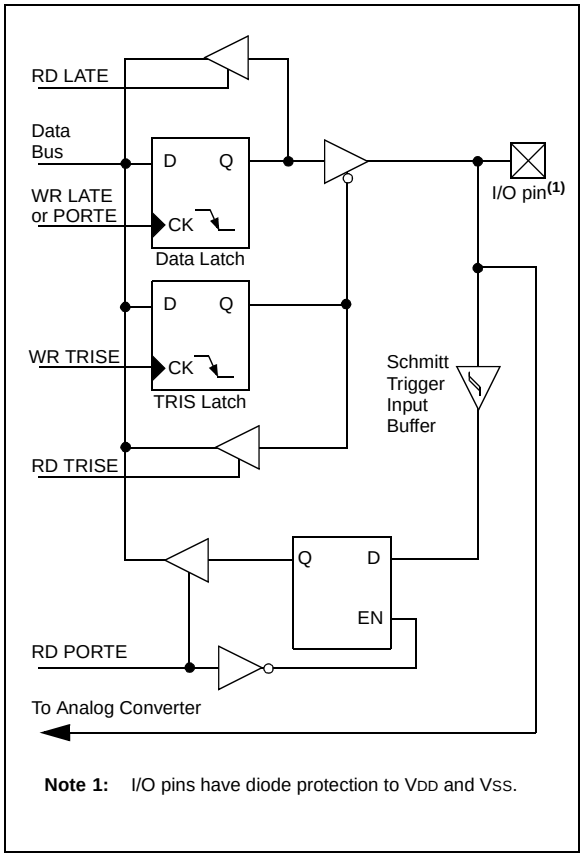
TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note:	On a Power-on Reset, these pins are configured as analog inputs.

EXAMPLE 9-5: INITIALIZING PORTE

```
CLRF   PORTE   ; Initialize PORTE by
               ; clearing output
               ; data latches
CLRF   LATE    ; Alternate method
               ; to clear output
               ; data latches
MOVLW  0x07    ; Configure A/D
MOVWF  ADCON1  ; for digital inputs
MOVLW  0x05    ; Value used to
               ; initialize data
               ; direction
MOVWF  TRISE   ; Set RE<0> as inputs
               ; RE<1> as outputs
               ; RE<2> as inputs
```

FIGURE 9-9: PORTE BLOCK DIAGRAM IN I/O PORT MODE



Note 1: I/O pins have diode protection to VDD and VSS.

12.0 TIMER2 MODULE

The Timer2 module is an 8-bit timer with a selectable 8-bit period. It has the following features:

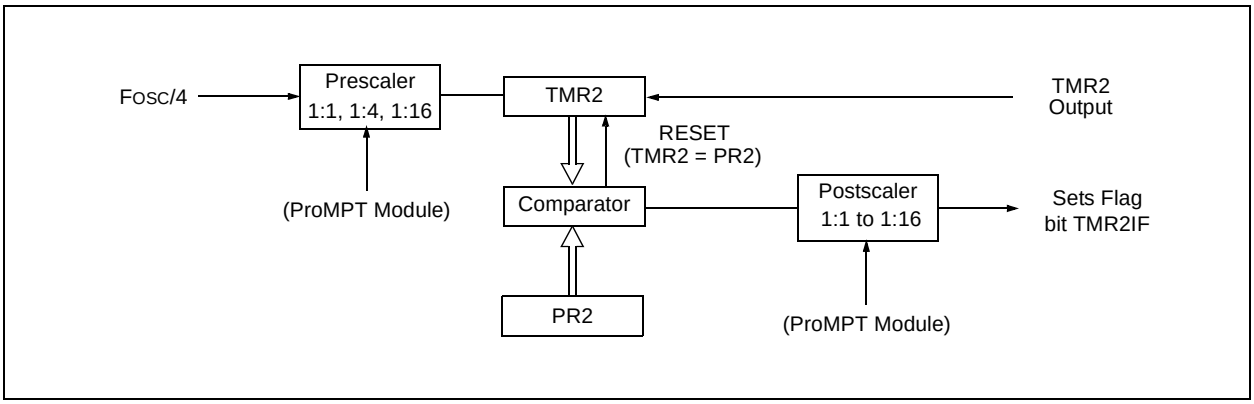
- Input from system clock at FOSC/4 with programmable input prescaler
- Interrupt on timer-to-period match with programmable postscaler

The module has three registers: the TMR2 counter, the PR2 period register, and the T2CON control register. The general operation of Timer2 is shown in Figure 12-1.

Additional information on the use of Timer2 as a time-base is available in Section 15.0 (PWM Modules).

Note: In PIC18FXX39 devices, Timer2 is used exclusively as a time-base for the PWM modules in motor control applications. As such, it is not available to users as a resource. Although their locations are shown on the device data memory maps, none of the Timer2 registers are directly accessible. Users should not alter the values of these registers.

FIGURE 12-1: TIMER2 BLOCK DIAGRAM



16.4.3.2 Reception

When the R/$\overline{W}$ bit of the address byte is clear and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register and the SDA line is held low ($\overline{ACK}$).

When the address byte overflow condition exists, then the no Acknowledge ($\overline{ACK}$) pulse is given. An overflow condition is defined as either bit BF (SSPSTAT<0>) is set, or bit SSPOV (SSPCON1<6>) is set.

An MSSP interrupt is generated for each data transfer byte. Flag bit SSPIF (PIR1<3>) must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

If SEN is enabled (SSPCON1<0> = 1), RC3/SCK/SCL will be held low (clock stretch) following each data transfer. The clock must be released by setting bit CKP (SSPCON<4>). See Section 16.4.4 (“Clock Stretching”), for more detail.

16.4.3.3 Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit and pin RC3/SCK/SCL is held low, regardless of SEN (see “Clock Stretching”, Section 16.4.4, for more detail). By stretching the clock, the master will be unable to assert another clock pulse until the slave is done preparing the transmit data. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, pin RC3/SCK/SCL should be enabled by setting bit CKP (SSPCON1<4>). The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 16-9).

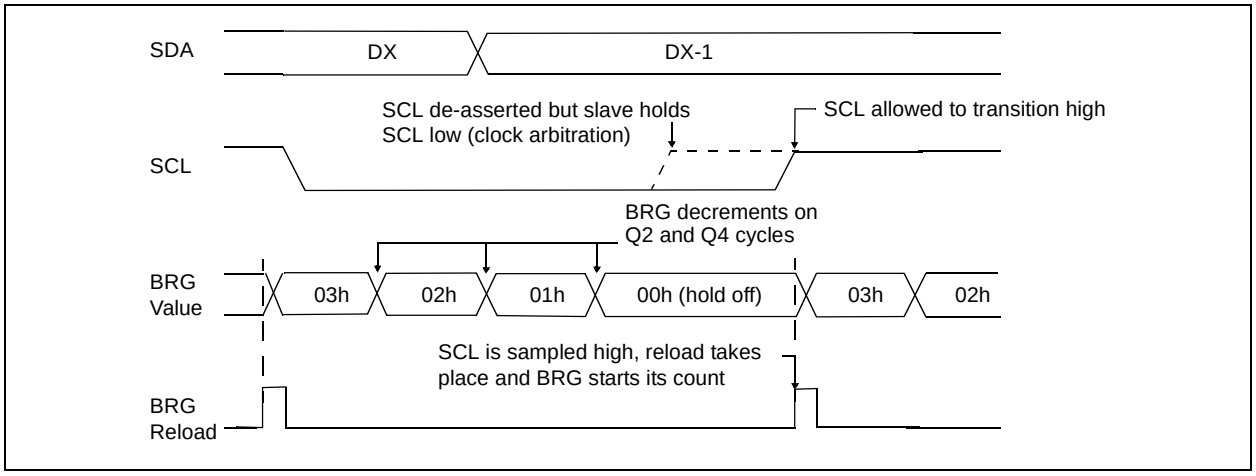
The $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line is high (not $\overline{ACK}$), then the data transfer is complete. In this case, when the $\overline{ACK}$ is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave monitors for another occurrence of the START bit. If the SDA line was low ($\overline{ACK}$), the next transmit data must be loaded into the SSPBUF register. Again, pin RC3/SCK/SCL must be enabled by setting bit CKP.

An MSSP interrupt is generated for each data transfer byte. The SSPIF bit must be cleared in software and the SSPSTAT register is used to determine the status of the byte. The SSPIF bit is set on the falling edge of the ninth clock pulse.

16.4.7.1 Clock Arbitration

Clock arbitration occurs when the master, during any receive, transmit or Repeated START/STOP condition, de-asserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the baud rate generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the baud rate generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count, in the event that the clock is held low by an external device (Figure 16-18).

FIGURE 16-18: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION



16.4.8 I²C MASTER MODE START CONDITION TIMING

To initiate a START condition, the user sets the START condition enable bit, SEN (SSPCON2<0>). If the SDA and SCL pins are sampled high, the baud rate generator is reloaded with the contents of SSPADD<6:0> and starts its count. If SCL and SDA are both sampled high when the baud rate generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low, while SCL is high, is the START condition and causes the S bit (SSPSTAT<3>) to be set. Following this, the baud rate generator is reloaded with the contents of SSPADD<6:0> and resumes its count. When the baud rate generator times out (TBRG), the SEN bit (SSPCON2<0>) will be automatically cleared by hardware, the baud rate generator is suspended, leaving the SDA line held low and the START condition is complete.

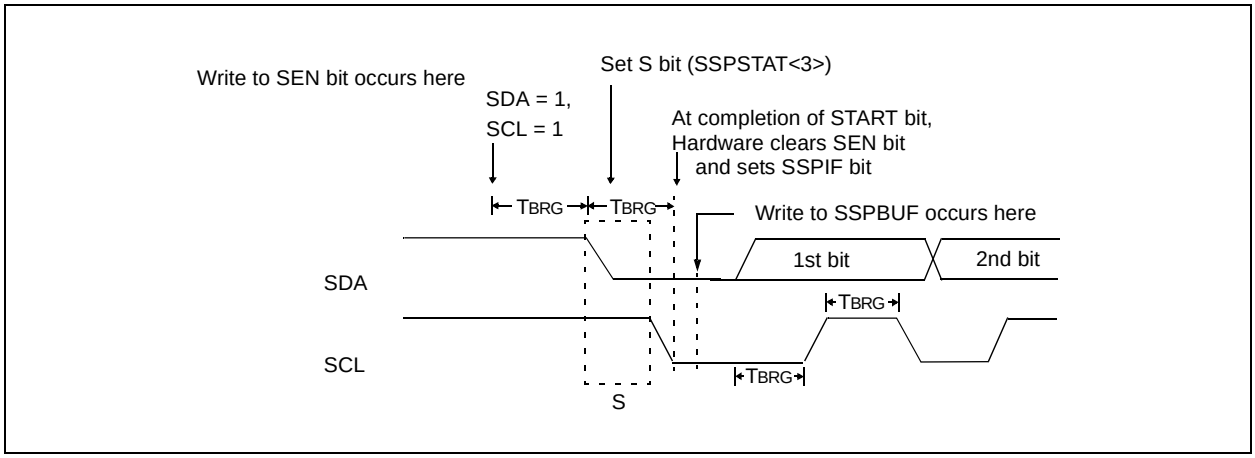
Note:	If at the beginning of the START condition, the SDA and SCL pins are already sampled low, or if during the START condition the SCL line is sampled low before the SDA line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCLIF is set, the START condition is aborted, and the I²C module is reset into its IDLE state.

16.4.8.1 WCOL Status Flag

If the user writes the SSPBUF when a START sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

Note:	Because queueing of events is not allowed, writing to the lower 5 bits of SSPCON2 is disabled until the START condition is complete.

FIGURE 16-19: FIRST START BIT TIMING



REGISTER 17-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D
bit 7							bit 0

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9**: 9-bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN**: Transmit Enable bit
1 = Transmit enabled
0 = Transmit disabled

Note: SREN/CREN overrides TXEN in SYNC mode.

bit 4 **SYNC**: USART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **Unimplemented:** Read as '0'

bit 2 **BRGH**: High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode

bit 1 **TRMT**: Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** 9th bit of Transmit Data
Can be Address/Data bit or a parity bit

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

20.3 Power-down Mode (SLEEP)

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared, but keeps running, the $\overline{PD}$ bit (RCON<3>) is cleared, the $\overline{TO}$ (RCON<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD} or V_{SS}, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D and disable external clocks. Pull all I/O pins that are hi-impedance inputs, high or low externally, to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

20.3.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on $\overline{MCLR}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change or a Peripheral Interrupt.

The following peripheral interrupts can wake the device from SLEEP:

1. PSP read or write.
2. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
3. TMR3 interrupt. Timer3 must be operating as an asynchronous counter.
4. CCP Capture mode interrupt.
5. Special event trigger (Timer1 in Asynchronous mode using an external clock).
6. MSSP (START/STOP) bit detect interrupt.
7. MSSP transmit or receive in Slave mode (SPI/I^2C).
8. USART RX or TX (Synchronous Slave mode).
9. A/D conversion (when A/D clock source is RC).
10. EEPROM write operation complete.
11. LVD interrupt.

Other peripherals cannot generate interrupts, since during SLEEP, no on-chip clocks are present.

External $\overline{MCLR}$ Reset will cause a device RESET. All other events are considered a continuation of program execution and will cause a “wake-up”. The $\overline{TO}$ and $\overline{PD}$ bits in the RCON register can be used to determine the cause of the device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared, if a WDT time-out occurred (and caused wake-up).

When the SLEEP instruction is being executed, the next instruction (PC + 2) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

20.3.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If an interrupt condition (interrupt flag bit and interrupt enable bits are set) occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt condition occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from SLEEP. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

MULLW **Multiply Literal with W**

Syntax: [*label*] MULLW k

Operands: $0 \le k \le 255$

Operation: (W) x k → PRODH:PRODL

Status Affected: None

Encoding:

0000	1101	kkkk	kkkk

Description: An unsigned multiplication is carried out between the contents of W and the 8-bit literal 'k'. The 16-bit result is placed in PRODH:PRODL register pair. PRODH contains the high byte. W is unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write registers PRODH: PRODL

Example: `MULLW 0xC4`

Before Instruction
W = 0xE2
PRODH = ?
PRODL = ?

After Instruction
W = 0xE2
PRODH = 0xAD
PRODL = 0x08

MULWF **Multiply W with f**

Syntax: [*label*] MULWF f [,a]

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (W) x (f) → PRODH:PRODL

Status Affected: None

Encoding:

0000	001a	ffff	ffff

Description: An unsigned multiplication is carried out between the contents of W and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte. Both W and 'f' are unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected. If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write registers PRODH: PRODL

Example: `MULWF REG, 1`

Before Instruction
W = 0xC4
REG = 0xB5
PRODH = ?
PRODL = ?

After Instruction
W = 0xC4
REG = 0xB5
PRODH = 0x8A
PRODL = 0x94

SUBWFB **Subtract W from f with Borrow**

Syntax: [*label*] SUBWFB f [,d [,a]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – (W) – ($\overline{C}$) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	10da	ffff	ffff

Description: Subtract W and the carry flag (borrow) from register 'f' (2's complement method). If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f' (default). If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' is 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: `SUBWFB REG, 1, 0`

Before Instruction
REG = 0x19 (0001 1001)
W = 0x0D (0000 1101)
C = 1
After Instruction
REG = 0x0C (0000 1011)
W = 0x0D (0000 1101)
C = 1
Z = 0
N = 0 ; result is positive

Example 2: `SUBWFB REG, 0, 0`

Before Instruction
REG = 0x1B (0001 1011)
W = 0x1A (0001 1010)
C = 0
After Instruction
REG = 0x1B (0001 1011)
W = 0x00
C = 1
Z = 1 ; result is zero
N = 0

Example 3: `SUBWFB REG, 1, 0`

Before Instruction
REG = 0x03 (0000 0011)
W = 0x0E (0000 1101)
C = 1
After Instruction
REG = 0xF5 (1111 0100)
; [2's comp]
W = 0x0E (0000 1101)
C = 0
Z = 0
N = 1 ; result is negative

SWAPF **Swap f**

Syntax: [*label*] SWAPF f [,d [,a]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<3:0>) → dest<7:4>,
(f<7:4>) → dest<3:0>

Status Affected: None

Encoding:

0011	10da	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W. If 'd' is 1, the result is placed in register 'f' (default). If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' is 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `SWAPF REG, 1, 0`

Before Instruction
REG = 0x53
After Instruction
REG = 0x35

NOTES:

23.2 DC Characteristics: PIC18FXX39 (Industrial, Extended) PIC18LFXX39 (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**				
		I/O ports:				
D030		with TTL buffer	Vss	0.15 VDD	V	VDD < 4.5V
D030A			—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D031		with Schmitt Trigger buffer	Vss	0.2 VDD	V	
		RC3 and RC4	Vss	0.3 VDD	V	
D032		$\overline{MCLR}$	Vss	0.2 VDD	V	
D032A		OSC1 (HS mode)	Vss	0.3 VDD	V	
D033		OSC1 (EC mode)	Vss	0.2 VDD	V	
	VIH	**Input High Voltage**				
		I/O ports:				
D040		with TTL buffer	0.25 VDD + 0.8V	VDD	V	VDD < 4.5V
D040A			2.0	VDD	V	4.5V ≤ VDD ≤ 5.5V
D041		with Schmitt Trigger buffer	0.8 VDD	VDD	V	
		RC3 and RC4	0.7 VDD	VDD	V	
D042		$\overline{MCLR}$, OSC1 (EC mode)	0.8 VDD	VDD	V	
D042A		OSC1 (HS mode)	0.7 VDD	VDD	V	
	IIL	**Input Leakage Current(1,2)**				
D060		I/O ports	.02	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at hi-impedance
D061		$\overline{MCLR}$	—	±1	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	±1	µA	Vss ≤ VPIN ≤ VDD
	IPU	**Weak Pull-up Current**				
D070	IPURB	PORTB weak pull-up current	50	450	µA	VDD = 5V, VPIN = VSS

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: Parameter is characterized but not tested.

FIGURE 24-15: TYPICAL AND MAXIMUM V_{OL} vs. I_{OL} (V_{DD} = 3V, -40°C TO +125°C)

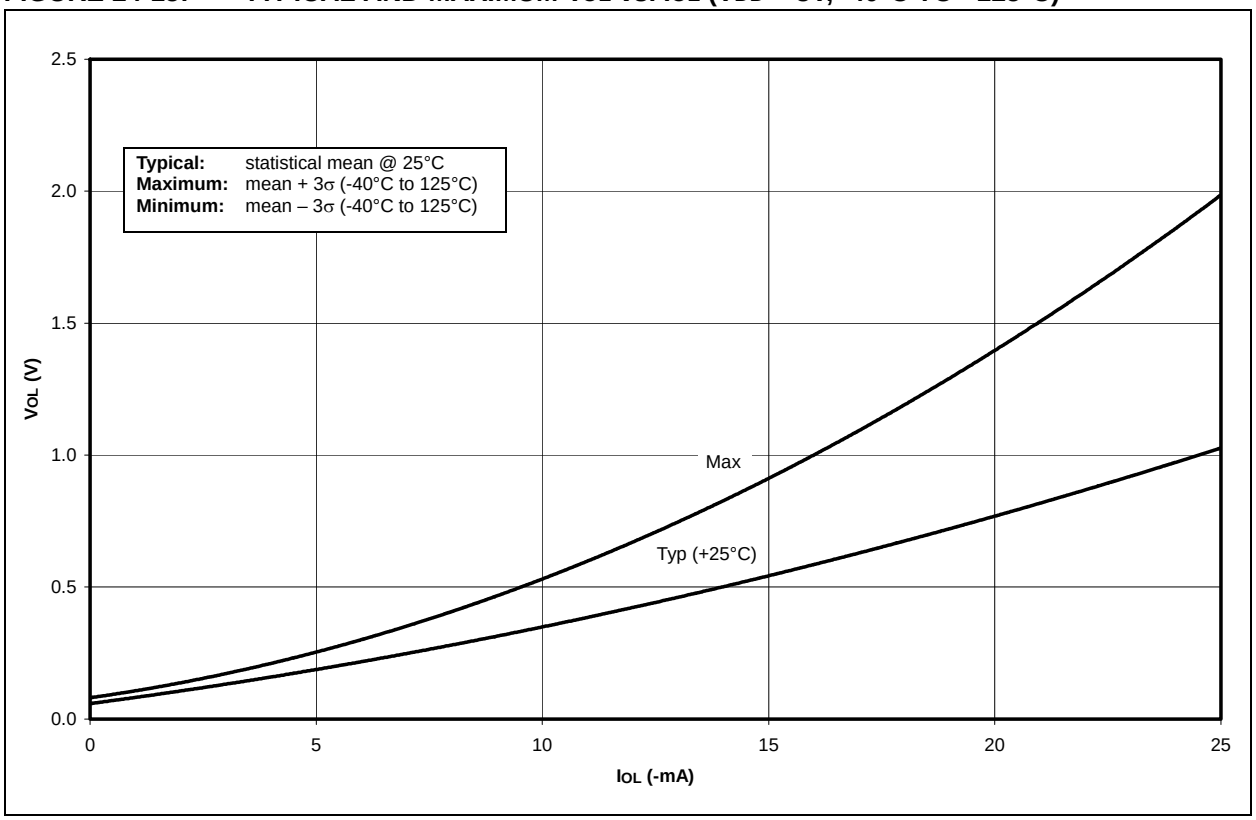
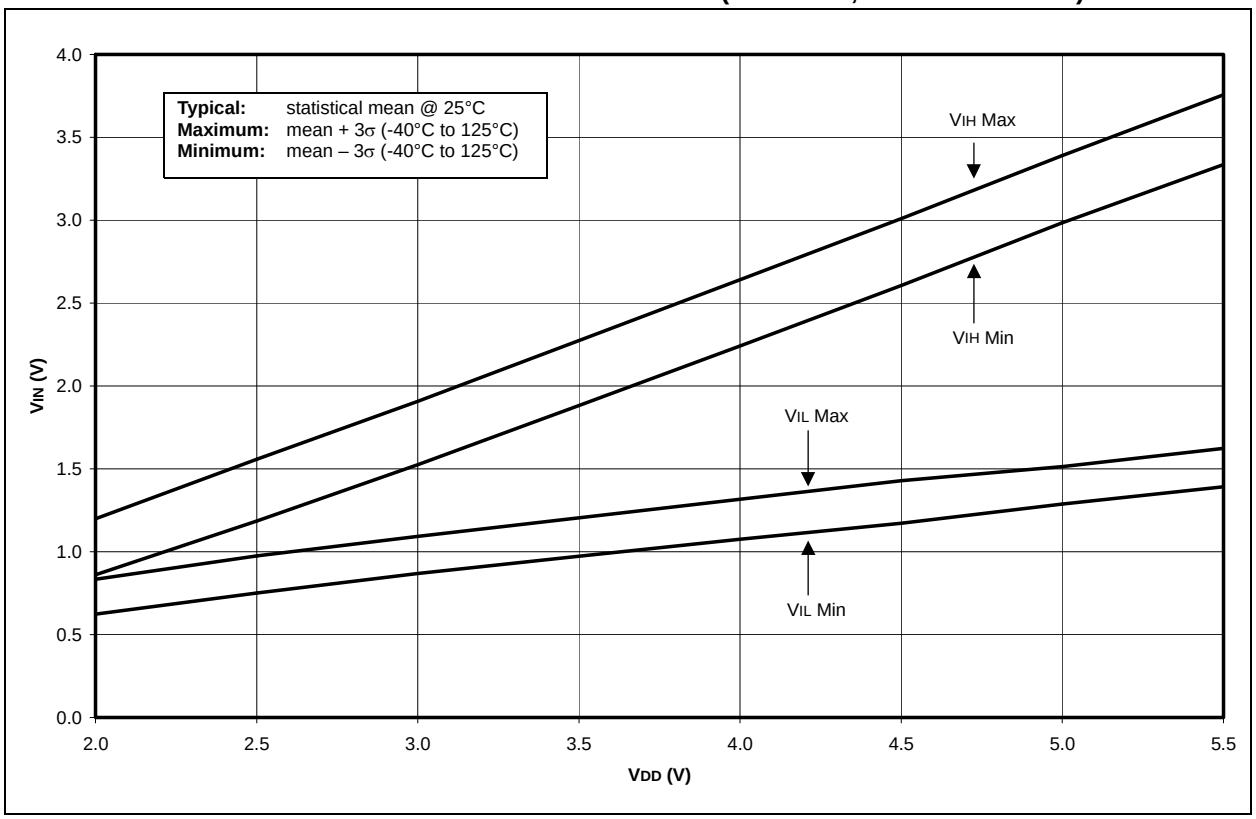


FIGURE 24-16: MINIMUM AND MAXIMUM V_{IN} vs. V_{DD} (ST INPUT, -40°C TO +125°C)



PIC18FXX39 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	–	X	/XX	XXX
Device		Temperature Range	Package	Pattern

Device	PIC18FXX39[1], PIC18FXX39T[2]; VDD range 4.2V to 5.5V PIC18LFXX39[1], PIC18LFXX39T[2]; VDD range 2.0V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	ML = QFN (Quad Flatpack, No Leads) P = PDIP PT = TQFP (Plastic Thin Quad Flatpack) SO = SOIC SP = Skinny Plastic DIP
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF4539 - I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301.

b) PIC18LF2439 - I/SO = Industrial temp., SOIC package, Extended VDD limits.

c) PIC18F4439 - E/P = Extended temp., PDIP package, normal VDD limits.

Note 1: F = Standard Voltage range
LF = Wide Voltage Range

2: T = in tape and reel - SOIC, QFN, and TQFP packages only.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)